

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

In the Claims:

Claim 1 (Original) An apparatus for processing one or more semiconductor wafers, comprising:

- a module for storing a wafer;
 - a plurality of vertically stacked processing modules for at least one of electropolishing the wafer and electroplating the wafer;
 - a cleaning module; and
 - a robot for transferring the wafer between the module for storing, the processing module, and the cleaning module,
- wherein the apparatus is divided into at least two sections characterized by separate frames.

Claim 2 (Original) The apparatus of claim 1, further including a pre-alignment module to align the wafer prior to processing.

Claim 3 (Original) The apparatus of claim 1, wherein the robot includes one or more end effectors for picking and transferring the wafer.

Claim 4 (Original) The apparatus of claim 1, wherein the robot is removable by rolling or sliding out from one of the at least two sections.

Claim 5 (Original) The apparatus of claim 1, wherein the robot includes,
a first end effector for transferring the wafer to the processing modules, and
a second end effector for transferring the wafer from the processing modules.

Claim 6 (Original) The apparatus of claim 1, further including a liquid delivery system for delivering process liquid to the processing modules.

Claim 7 (Original) The apparatus of claim 6, wherein the liquid delivery system includes a surge suppressor.

Claim 8 (Original) The apparatus of claim 6, wherein the liquid delivery system includes a controller to modulate a flow rate of the process liquid.

Claim 9 (Original) The apparatus of claim 6, wherein the liquid delivery system is housed in a containment tray.

Claim 10 (Original) The apparatus of claim 6 wherein the apparatus includes an exhaust to remove gases from the processing modules.

Claim 11 (Original) A method for at least one of electropolishing and electroplating a semiconductor wafer in a process assembly, comprising:

- transferring a wafer to one of a plurality of stacked processing modules with a first end effector;

- electropolishing or electroplating the wafer in the processing module;

- transferring the wafer from the processing module to a cleaning module with a second end effector; and

- cleaning the wafer in the cleaning module, wherein the process assembly is divided into at least two sections characterized by separate frames.

Claim 12 (Original) The method of claim 11, further wherein transferring the wafer includes using a robot and wherein the robot is configured to slide or roll out of the process assembly.

Claim 13 (Original) The method of claim 11, further including delivering liquid to the processing module through a supply line, wherein a surge suppressor is associated with the supply line.

Claim 14 (Original) The method of claim 11, further including removing gases from the processing module through an exhaust system.

Claims 15-137 (Canceled).